

**Amendments to the Specification:**

**Please replace the paragraph beginning on page 1, line 8 of the application with the following amended paragraph:**

Semiconductor packaged devices are continually being designed to be smaller in size. One aspect of manufacturing such devices involves connecting the semiconductor die to the electrically conductive leads to allow the die to communicate with external electrical systems. Typically, electrical wires are connected to these components with a standard stitch bonding (SSB) technique. FIG. 1 illustrates a side plan, diagrammatic view of a semiconductor die 100 that has been connected to a contact lead 102 with a standard stitch bonded wire 104. A capillary 106 is used to bond wire 104 between die 100 and lead 102. Capillary 106 is a hollow tube device through which wire 104 is extruded. Die 100 is shown to be bonded onto a die attach pad ~~106~~ 108 with an adhesive material ~~110~~ 108. Contact lead 102 is positioned adjacent to die attach pad ~~106~~ 108.

**Please insert the following paragraph after the paragraph that ends on page 5, line 17 of the application:**

FIG. 7 illustrates a perspective view of a stacked die assembly in accordance with another embodiment of the invention.

**Please insert the following paragraph after the paragraph that ends on page 11, line 4 of the application:**

FIG. 7 illustrates another stacked die wiring configuration. In this embodiment, bonding wires are used to facilitate die-to-die bonding. When appropriate, some of the die-to-die bonding wires may be crossed and the ball bonds for the die-to-die bonding wires may be formed on either the upper or lower stacked die.